

Amendments to the Specification:

Please replace the paragraph beginning at page 19, line 1, with the following amended paragraph:

-- In order to form the divided solder resist layer 20, masking is made on a conventional screen correspondingly to the sections, and ~~the only resin only the resin~~ has to be applied. In case of a solder resist of the adhesion type, which recently has begun to be adopted, a gap is formed, and then only the solder resist has to be allowed to adhere. In case of a solder resist using a photosensitive resin, the resin is applied, and then only the resin has to be exposed and developed so as to split and/or divide the solder resist layer. The solder resist layer whose divided sections are connected to one another at least in part can be formed by controlling a line width of a screen mask that is used when a solder resist coating liquid is applied. --

Please replace the paragraph beginning at page 22, line 1, with the following amended paragraph:

-- In the film carrier tape for mounting electronic parts of the present invention, the solder resist layer is formed in such a manner that the layer is split or divided, whereby warpage distortion of a film carrier is reduced, and the film carrier tape for mounting electronic part parts exhibits high reliability. --

Please replace the paragraph beginning at page 24, line 3, with the following amended paragraph:

-- From the film carriers formed near the lengthwise center of the resulting film carrier tape for mounting electronic part parts, 12 film carriers in continuous six rows were arbitrarily selected, and warpage distortion of these film carriers were was measured. --

Please replace the paragraph beginning at page 25, line 5, with the following amended paragraph:

-- From the film carriers of the resulting film carrier tape for mounting electronic parts, 12 film carriers in continuous six rows were arbitrarily selected in the same manner as in Example 1, and warpage distortion of these film carriers were measured. --

Please replace the paragraph beginning at page 25, line 20, with the following amended paragraph:

-- In the film carrier tape for mounting electronic parts of the present invention, the solder resist layer is split or divided into plural sections, so that a stress caused by shrinkage occurring in the curing of the solder resist ink is scattered. In the film carrier tape for mounting electronic parts of the present invention, therefore, warpage distortion of a film carrier attributable to the cure shrinkage of the solder resist layer is remarkably reduced, and precision in the mounting of electronic part parts is surely enhanced. --